## **Description**

The SI7613DN-T1-GE3 uses advanced trench

technology to provide excellent  $R_{\text{DS}(\text{ON})}$ , low gate

charge and operation with gate voltages as low

as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.



DFN3X3-8L

### **General Features**

 $V_{DS} = -20V I_{D} = -60A$ 

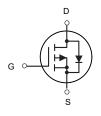
 $R_{DS(ON)}$  < 10 m $\Omega$  @  $V_{GS}$ =-4.5V



Battery protection

Load switch

Uninterruptible power supply



P-Channel MOSFET

## **Package Marking and Ordering Information**

| Product ID      | Pack      | Brand      | Qty(PCS) |
|-----------------|-----------|------------|----------|
| SI7613DN-T1-GE3 | DFN3X3-8L | HXY MOSFET | 5000     |

## Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

| Symbol                                | Parameter  | Rating     | Units |
|---------------------------------------|--|------------|-------|
| VDS                                   | Drain-Source Voltage   | -20        | V     |
| VGS                                   | Gate-Source Voltage  | ±12        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25°C  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | -60        | А     |
| I <sub>D</sub> @T <sub>C</sub> =100°C | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | -30        | А     |
| IDM                                   | Pulsed Drain Current <sup>2</sup>                            | -78        | А     |
| P <sub>D</sub> @T <sub>C</sub> =25°C  | Total Power Dissipation <sup>4</sup>                         | 22         | W     |
| TSTG                                  | Storage Temperature Range                                    | -55 to 150 | °C    |
| TJ                                    | Operating Junction Temperature Range                         | -55 to 150 | °C    |
| R <sub>θ</sub> JA                     | Thermal Resistance Junction-ambient <sup>1</sup>             | 75         | °C/W  |
| R₀JC                                  | Thermal Resistance Junction-Case <sup>1</sup>                | 4.2        | °C/W  |

## P-Channel Enhancement Mode MOSFET

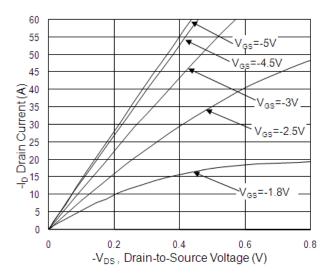
## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

| Symbol                                    | Parameter                                      | Conditions  | Min. | Тур.   | Max.  | Unit  |
|---|--|---|------|--------|-------|-------|
| BV <sub>DSS</sub>                         | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA                          | -20  |        |       | V     |
| $\triangle BV_{\text{DSS}}/\triangle T_J$ | BV <sub>DSS</sub> Temperature Coefficient      | Reference to 25°C , I <sub>D</sub> =-1mA                              |      | -0.012 |       | V/°C  |
|   |  | V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-10A                         |      | 7      | 10    |       |
| R <sub>DS(ON)</sub>                       | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =-2.5V , I <sub>D</sub> =-8A                          |      | 9      | 12    | mΩ    |
|   |  |   |      |        |       |       |
| $V_{GS(th)}$                              | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA             | -0.4 | -0.7   | -1.0  | V     |
| $\triangle V_{GS(th)}$                    | V <sub>GS(th)</sub> Temperature Coefficient    | VGS-VDS , ID230UA   |      | 2.94   |       | mV/°C |
| IDSS                                      | Drain-Source Leakage Current                   | V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C    |      |        | 1     | uA    |
| I <sub>GSS</sub>                          | Gate-Source Leakage Current                    | $V_{GS}=\pm 12 V$ , $V_{DS}=0V$                                       |      |        | ±100  | nA    |
| gfs                                       | Forward Transconductance                       | V <sub>DS</sub> =-5V , I <sub>D</sub> =-10A                           |      | 43     |       | S     |
| $Q_g$                                     | Total Gate Charge (-4.5V)                      |   |      | 35     |       |       |
| Qgs                                       | Gate-Source Charge                             | V <sub>DS</sub> =-10V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-10A |      | 5.0    |       | nC    |
| Q <sub>gd</sub>                           | Gate-Drain Charge                              |   |      | 10     |       |       |
| T <sub>d(on)</sub>                        | Turn-On Delay Time                             |   |      | 12.0   |       |       |
| Tr  | Rise Time                                      | V <sub>DD</sub> =-10V , V <sub>GS</sub> =-4.5V ,                      |      | 40.0   |       | no    |
| T <sub>d(off)</sub>                       | Turn-Off Delay Time                            | R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-10A                            |      | 30     |       | ns    |
| T <sub>f</sub>                            | Fall Time                                      |   |      | 10     |       |       |
| Ciss                                      | Input Capacitance                              |   |      | 2800   |       |       |
| Coss                                      | Output Capacitance                             | V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz                  |      | 690    |       | pF    |
| Crss                                      | Reverse Transfer Capacitance                   |   |      | 590    |       |       |
| ls  | Continuous Source Current <sup>1,4</sup>       | Vo=Vo=0V Force Current  |      |        | -60.0 | Α     |
| lsм                                       | Pulsed Source Current <sup>2,4</sup>           | ──V <sub>G</sub> =V <sub>D</sub> =0V , Force Current                  |      |        |       | Α     |
| V <sub>SD</sub>                           | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C      |      |        | -1.2  | V     |
| t <sub>rr</sub>                           | Reverse Recovery Time                          | IF=-10A , dI/dt=100A/μs ,   |      | 27     | -     | nS    |
| Qrr                                       | Reverse Recovery Charge                        | T <sub>J</sub> =25°C  |      | 17.8   |       | nC    |

#### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

## **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

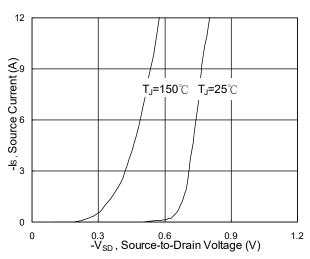


Fig.3 Forward Characteristics of Reverse

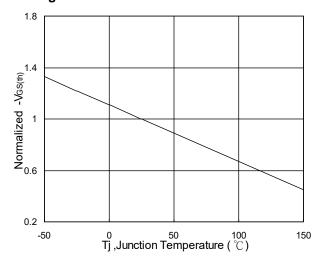


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

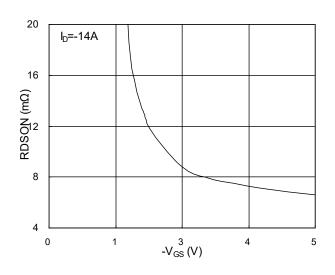


Fig.2 On-Resistance vs. G-S Voltage

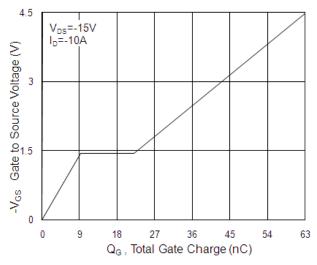


Fig.4 Gate-charge Characteristics

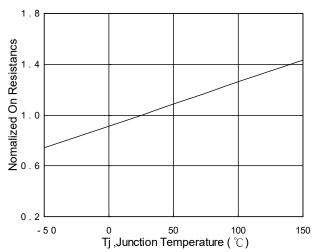
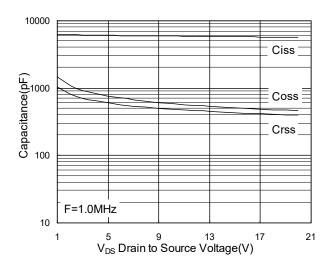


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





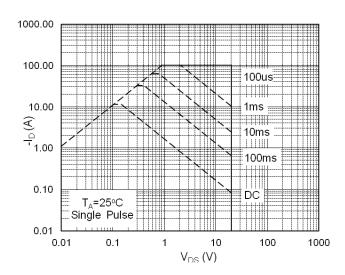


Fig.7 Capacitance

Fig.8 Safe Operating Area

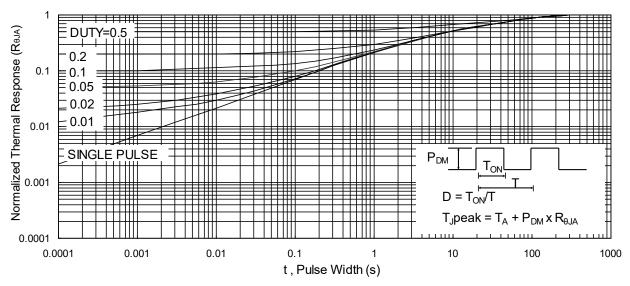
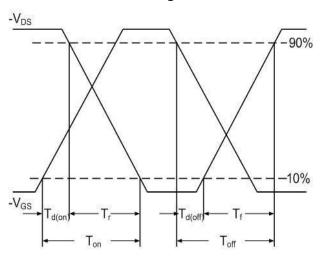


Fig.9 Normalized Maximum Transient Thermal Impedance



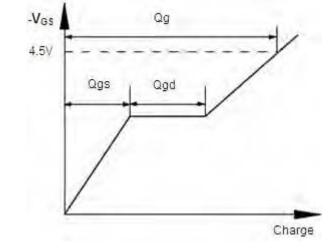
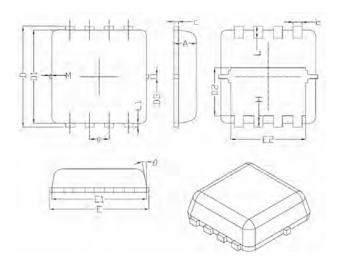


Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform

## **DFN3X3-8L Package Information**



| Symbol | Dimensions In Millimeters |         |                 |  |
|--------|---------------------------|---------|-----------------|--|
| Symbol | Min.                      | Nom.    | Max.            |  |
| A      | 0.70                      | 0.75    | 0.80            |  |
| b      | 0.25                      | 0.30    | 0.35            |  |
| С      | 0.10                      | 0.15    | 0.25            |  |
| D      | 3.25                      | 3.35    | 3.45            |  |
| D1     | 3.00                      | 3.10    | 3.20            |  |
| D2     | 1.48                      | 1.58    | 1.68            |  |
| D3     | -                         | 0.13    | -               |  |
| E      | 3.20                      | 3.30    | 3.40            |  |
| E1     | 3.00                      | 3.15    | 3.20            |  |
| E2     | 2.39                      | 2.49    | 2.59            |  |
| е      |                           | 0.65BSC |                 |  |
| Н      | 0.30                      | 0.39    | 0.50            |  |
| L      | 0.30                      | 0.40    | 0.50            |  |
| L1     | -                         | 0.13    | -               |  |
| M      | *                         | *       | 0.15            |  |
| θ      |                           | 10°     | 12 <sup>°</sup> |  |



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP NTMC083NP10M5L NVMFS2D3P04M8LT1G BXP7N65D
BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR
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